

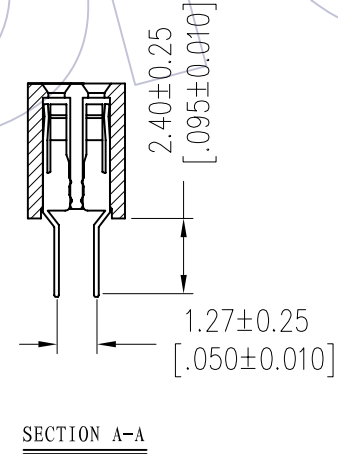
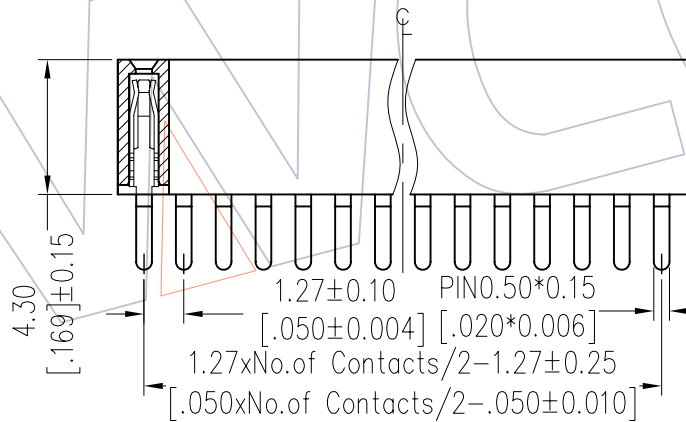
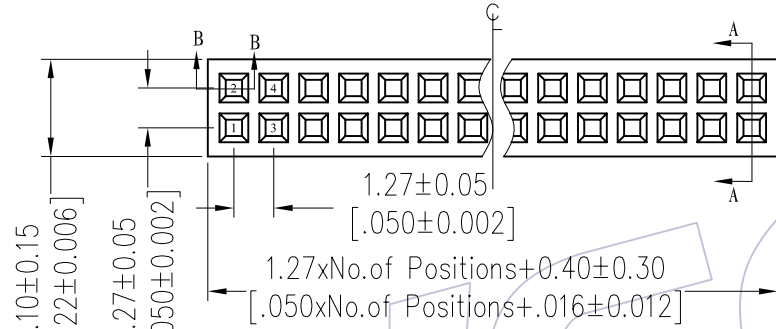
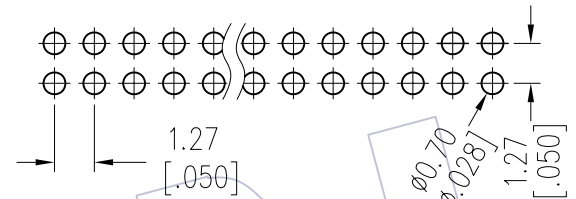
HSF

NOTES:

Current Rating: 1.0AMP
 Contact Resistance: 20mΩ Max
 Withstand Voltage: 500V AC/DC
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
 Contact plating: Au Or Sn over Ni
 Insulator Material: PA9T+30%G.F UL94V-0

Recommended P.C.B Layout (Top Side)
 (PCB BOARD TOLERANCE ±0.05)



SECTION B-B

SECTION A-A

Ordering Information

2344-2 XX S XX CUN T 1

No. of Pins per Row: 02-50 Pin

Contact Plating:
 G0=Gold Flash
 G3=10μ"Gold
 G4=15μ"Gold
 G5=30μ"Gold
 S0=Gold Flash/Tin
 S3=10μ"Gold/Tin
 S4=15μ"Gold/Tin
 S5=30μ"Gold/Tin
 SN=Tin

Packing:
 T=Tube
 P=Tube+CAP
 R=Tape&Reel+CAP

Item	Pitch	Mating
Standard	1.27	1310/1315/1320/3131/3133/3100
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
				x.x ±0.40	JYHuang	2012/07/09	UNIT	mm	2344-2XXSXXCUNT1
				x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE:
				x.xxx ±0.15	APPROVE	DATE	SHEET	1/1	FH1.27mm DUAL ROW 180° DIP H=4.30
				Angle ± 3'			PROJ.	Customer NO.	
				DIM TOL					